

REMARKS

Claim 9 is currently pending in the subject application.

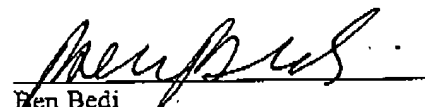
Claim 9 recites "a sublayer film provided between the substrate and the photoresist pattern." It is well known to those skilled in the art that according to a typical method used for evaluating photoresist patterns, a line shaped photoresist pattern is formed on a substrate, which extends in the vertical direction to the cleavage plane of the substrate to create an evaluation substrate that is cut at the cleavage plane to observe the cross section of the photoresist pattern. Unfortunately, if the sublayer film is washed away or collapsed, the observation and evaluation of the cross section is not possible. (see Specification at pages 1-2.) To prevent the sublayer and the photoresist pattern layer thereon from being washed away or collapsed, pending claim 9 recites a reinforcing section. (see also Specification at page 2, lines 11-12.).

In contrast, Kamijima does not disclose the presence of a sublayer under photoresist layer 14 in portion 17.

Therefore, Kamijima does not show or suggest the invention of the present application.

Respectfully submitted,

Date: July 5, 2006


Ben Bedi
Reg. No. 39,904

DECHERT LLP
Customer No. 37509
Tel: 650.813.4800

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being forwarded via facsimile to Examiner Christopher G. Young in Group No. 1756 at facsimile number 571.273.8300 located at Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA, 22313-1450, on:

Date: July 5, 2006


Yolene Yarralde-Owen